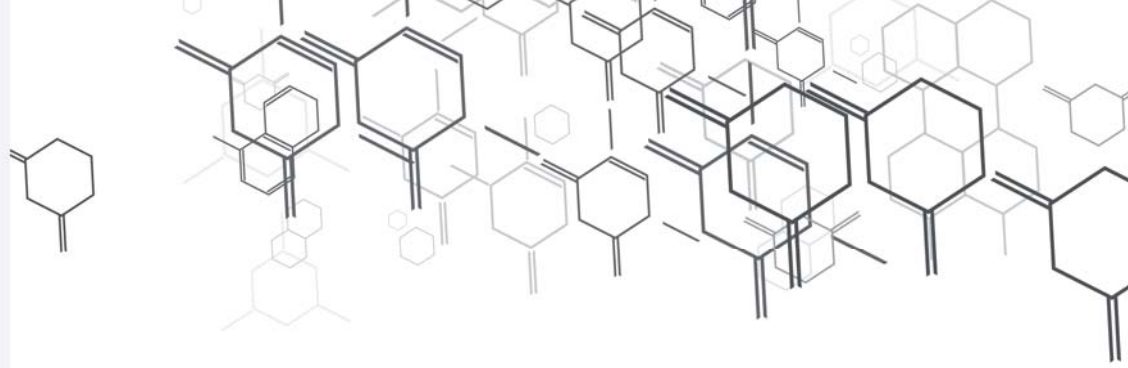


Solutions for Wafer-level MEMS



Wafer-level packaging is the key for low cost and high reliability of final MEMS devices and the shift from ceramic and metallic hermetic packages to wafer-level packages is a well established and irreversible technological trend of the MEMS industry.

This shift requires to be supported by an advanced getter technology capable to address the sophisticated geometry requirements of the MEMS/MOEMS technology, particularly allowing to bypass the impairments caused by the handling and welding of discrete getter components in such miniaturized devices, while of course still delivering a highly reliable performance in terms of impurity removal.

Exploiting the new Page film technology, PageWafer is SAES' innovative solution to integrate getter material films into wafer-to-wafer bonded MEMS: acting as the cap wafer of the MEMS package, PageWafer ensures the performance stability along the device lifetime (5-20 years).

In PageWafer, the getter film is selectively placed inside cavities with depths ranging from a few to hundreds of microns. A SAES proprietary technology allows the customization of the pattern of Page film. Main advantage of the Page technology is the enhanced getter mechanical stability assuring no loose particles and good adhesion to the cap wafer substrates.

SAES Getters is equipped to supply a state of the art coating service process to customers cap wafers.



Boost your product performance with SAES Getters solutions:

- PageWafer

making innovation happen, together

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